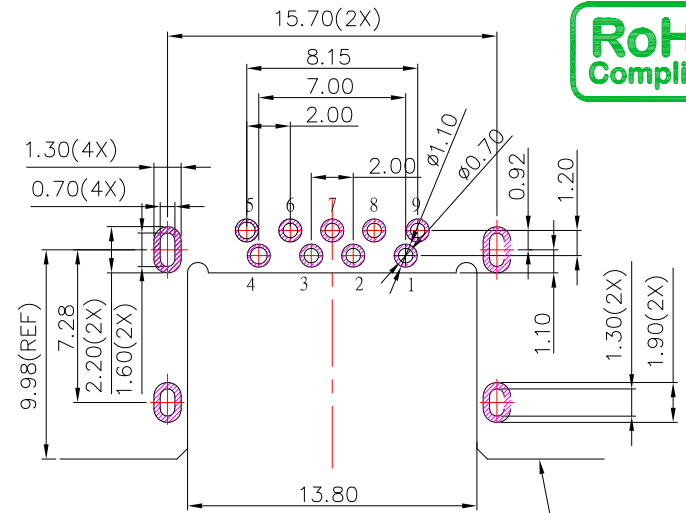
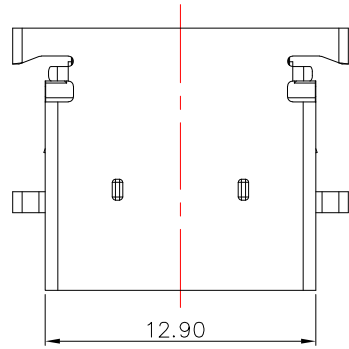




SUA-110E7-30xx-S277

鍍層厚度: HOUSING:

Blank : 1u"	Blank : Blue
2 : 15u"	K : BLack
3 : 30u"	

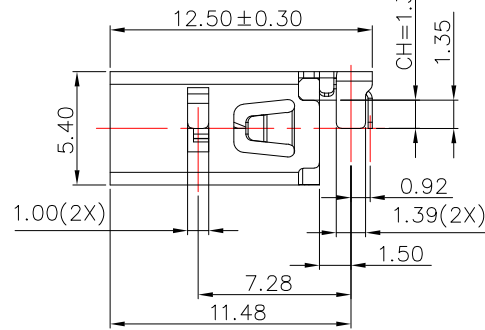


RECOMMENDED PCB LAYOUT
TOP VIEW

PCB EDGE

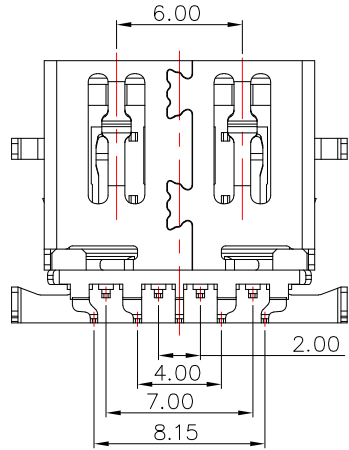
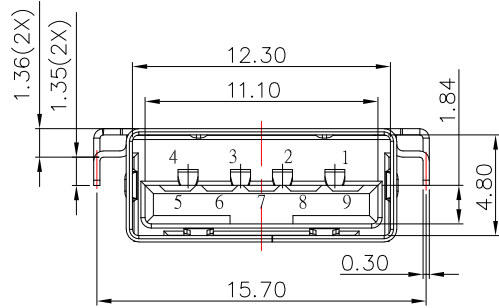
NOTE:

- 1.MATERIAL:
 - 1.1 Housing: LCP
 - 1.2 Contact: Phosphor Bronze
 - 1.3 Shell: SUS
- 2.Finish:
 - 2.1 Contact: Plated Gold in Mating Area ;
Tin Plated on Solder Balls ;
Nickel under plated overall
 - 2.2 Shell: Nickel under Plated surface layer
- 3.SPECIFICATION:
 - 3.1 Rate: 30V DC , 1.8 A(VBUS & GND);0.25 A(other pin);
 - 3.2 Insulator Resistance:100MΩ Min
 - 3.3 Dielectric Strength: 100V AC
 - 3.4 Contact Resistance: 30mΩ Max
 - 3.5 Operation Temperature: -25°C ~ +85°C
 - 3.6 Insertion Force: 35 N
 - 3.7 Extraction Force: 10 N



USB 3.0 PIN ASSIGNMENTS

Pin #	SIGNAL NAME	DESCRIPTION	MATING SEQUENCE
1	VBUS	POWER	SECOND
2	D-	USB 2.0 DIFFERENTIAL PAIR	THIRD
3	D+		
4	GND	GROUND FOR POWER RETURN	SECOND
5	StdA_SSRX-	SUPERSPEED RECEIVER DIFFERENTIAL PAIR	LAST
6	StdA_SSRX+		
7	GND_DRAIN	GROUND FOR SIGNAL RETURN	
8	StdA_SSTX-	SUPERSPEED TRANSMITTER DIFFERENTIAL PAIR	
9	StdA_SSTX+		
Shell	Shield	CONNECTOR METAL SHELL	FRIST



2	更新Contact材質	Jack	060625
1	更新圖面	Jack	061920
ITEM NO.	DESCRIPTION	DRAWN	DATE

TOLERANCE UNLESS OTHERWISE STATED :	Up to 5 ±0.2	3RD. ANGEL'S	UNITS	MM
	Above 5 ~ 15 ±0.3			
	Above 15 ~ 30 ±0.4			
	Above 30 ~ 50 ±0.5			
	Angle ±0.3			

DRAWN BY:	DATE	MAT'L	TITLE	CONNECTOR
Jack Lu	06/06/25			
CHECKED BY:	DATE	FINISH	MODLE	USB AF 3.0 DIP 沉板, 板上H:1.36mm L:12.5, 無捲邊反向
Jacky Chen	06/06/25			
APPROVED BY:	DATE	SCALE	DWG NO.	SUA-110E7-30xx-S277
Tony Kao	06/06/25	1 : 1		
		SHEET NO.	PART NO.	SUA-110E7-30xx-S277
		1 of 1		
				SIZE A4
				VER R2